

Gate Driver Unit 2EG01XBxN18N

■ Overview

2EG01XBxN18N is a dual channel gate driver designed for SiC MOSFET power module.
 This gate driver unit contains a built-in isolated DC/DC converter and gate drive circuit.
 After mounting the gate resistors, It is ready to use by mounting it on the SiC MOSFET power module.

■ Features

- Ideal for drive of SiC MOSFET Power module
- Gate voltage : +15V/-7V
- Gate resistor : Open (lead resistor mounting possible)
- Short circuit detection voltage : 9.5V(TYP)
- ALL-IN-ONE (Built-in isolated DC / DC converter and gate drive circuit)
- Low parasitic capacitance (12pF(TYP)) ; highly resistant to common-mode noise.
- Fast response : About 130nsec(typ)
- The isolation for primary-secondary signal used fast response isolator.
- Dielectric withstand voltage : AC5000V
- Insulation distance (clearance / creepage) : 12mm/16mm (As for Gate driver PCB) *Refer to P6 for details
- DC/DC converter input voltage : 13~28V
- Power supply for gate driver input voltage : 13~28V
- Signal input voltage : 3.3~15V or 15V
- Overload protection (DC/DC converter)
- Overheat protection (DC/DC converter)
- Desaturation protection (Gate drive circuit)
- Soft turn-off function (Gate drive circuit)
- Fault signal output function (Gate drive circuit)
- Under-voltage lockout(UVLO) (Gate drive circuit)
- Direct mode / Half bridge mode can be switched. (Gate drive circuit)
- Miller clamp function (Gate drive circuit)
- Safety standards : UL508(file no.E243511) (DC/DC converter only)
- Reinforced isolation according to IEC 60664-1 (IEC61800-5-1, IEC62477-1, IEC62109-1, etc.)
- UL compliant (UL1741, UL508, etc.)

■ Application

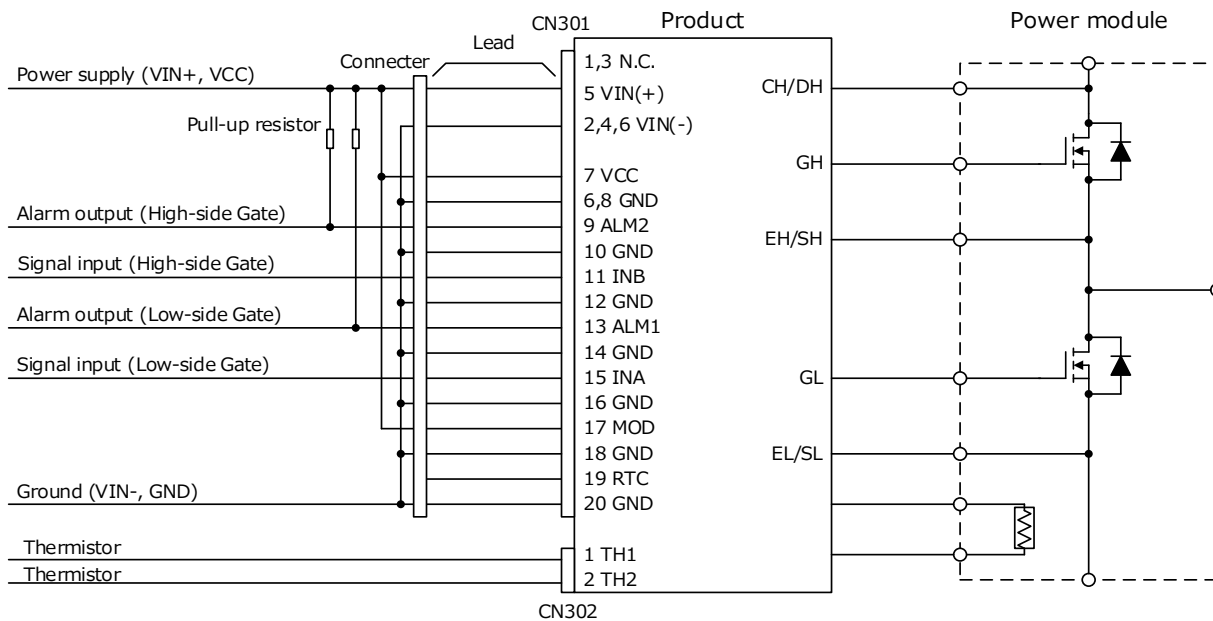
Industrial inverter, power conditioner, etc.

■ Module information

Part number	Signal input voltage	Miller clamp	Coating	Status
2EG01XBCN18N	3.3 to 15V	Yes	No	In development
2EG01XBDN18N	15V	Yes	No	In development

This target specification is subject to be changed without notice.

■ Circuit Image



■ Pin Connection

CN301 : RA-H201TD (JST)

Pin No.	Name	Function	Pin No.	Name	Function
1	N.C.	Unused	2	VIN(-)	Power supply for DC/DC converter(-)
3	N.C.	Unused	4	VIN(-)	Power supply for DC/DC converter(-)
5	VIN(+)	Power supply for DC/DC converter(+)	6	VIN(-)	Power supply for DC/DC converter(-)
7	VCC	Power supply for drive circuit	8	GND	Ground for drive circuit
9	ALM2	Alarm signal output 2 (High side)	10	GND	Ground for drive circuit
11	INB	Control input B (High side)	12	GND	Ground for drive circuit
13	ALM1	Alarm signal output 1 (Low side)	14	GND	Ground for drive circuit
15	INA	Control input A (Low side)	16	GND	Ground for drive circuit
17	MOD	Mode select	18	GND	Ground for drive circuit
19	RTC	Restart time of protection circuit control	20	GND	Ground for drive circuit

※Reference receptacle : RA-S201T (JST)

CN302 : B2B-ZR-SM4 (JST)

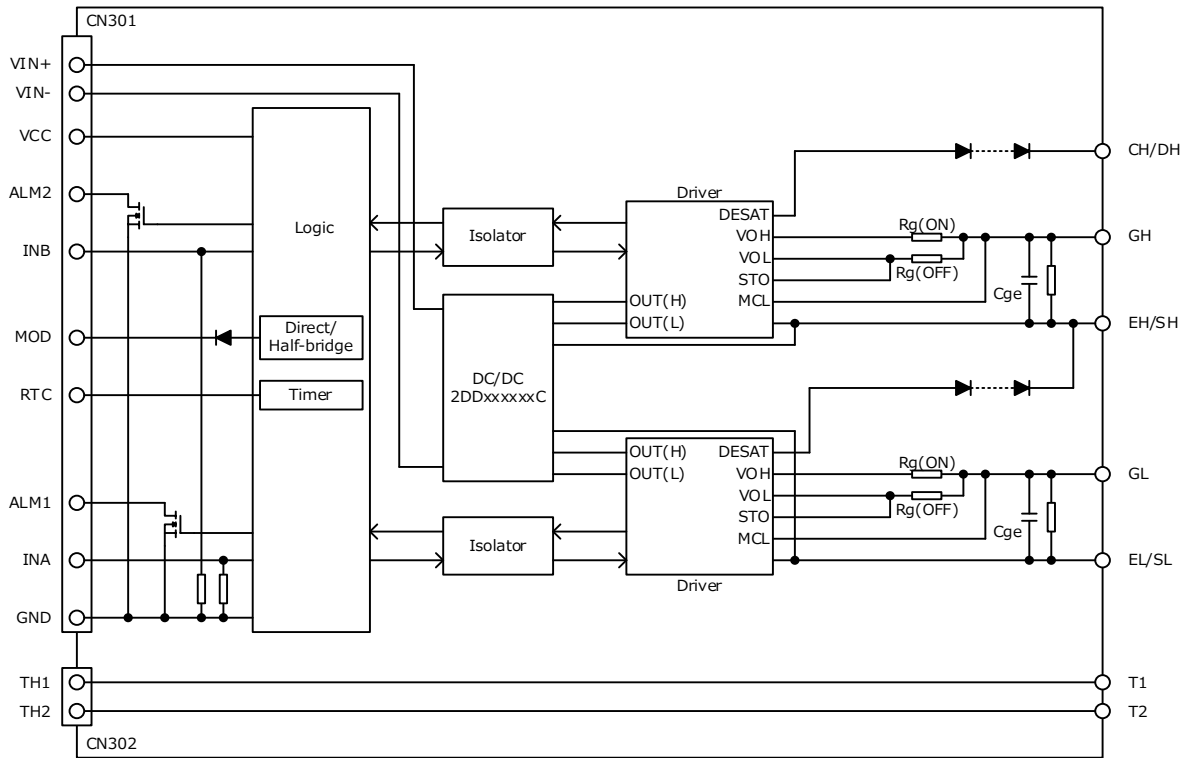
Pin No.	Name	Function
1	TH1	Thermistor connection
2	TH2	Thermistor connection

※Reference receptacle : ZHR-2 (JST)

Connection on the power module

Name	CH	Function
CH/DH	1	Drain connection, High side
GH	1	Gate connection, High side
EH/SH	1	Source connection, High side
GL	2	Gate connection, Low side
EL/SL	2	Source connection, Low side
T1	-	Thermistor connection
T2	-	Thermistor connection

Internal Block Diagram



I/O Condition Table

No.	Status	Input					Output				Note	
		OUT(H)	CH/DH	EH/SH	MOD	INB	INA	ALM2	ALM1	GH		GL
1	V _{OUT} UVLO	UVLO	X	X	X	X	X	L	L	L	L	Output state in UVLO (V _{out} < UVLO _{th})
2	G-S short	○	X	X	X	X	X	L	L	SD	SD	Output state in Gate-Source short
3	Normal operation	○	-	L	H	-	L	-	Hi-Z	-	L	Low side I/O state in direct mode (MOD pin H)
4		○	-	L	H	-	H	-	Hi-Z	-	H	
5		○	L	-	H	L	-	Hi-Z	-	L	-	High side I/O state in direct mode (MOD pin H)
6		○	L	-	H	H	-	Hi-Z	-	H	-	
7		○	L	L	L	L	X	Hi-Z	Hi-Z	L	L	I/O state in half-bridge mode (MOD pin L)
8		○	L	L	L	H	L	Hi-Z	Hi-Z	H	L	
9		○	L	L	L	H	H	Hi-Z	Hi-Z	L	H	
10	Short circuit detection (L)	○	-	Hi-Z	H	-	L	-	Hi-Z	-	L	I/O state during low side DESAT protection in direct mode
11		○	-	Hi-Z	H	-	H	-	L	-	L	
12		○	-	Hi-Z	L	H	L	-	Hi-Z	-	L	I/O state during low side DESAT protection in half-bridge mode
13	○	-	Hi-Z	L	H	H	-	L	-	L		
14	Short circuit detection (H)	○	Hi-Z	-	H	L	-	Hi-Z	-	L	-	I/O state during high side DESAT protection in direct mode
15		○	Hi-Z	-	H	H	-	L	-	L	-	
16		○	Hi-Z	-	L	H	H	Hi-Z	-	L	-	I/O state during high side DESAT protection in half-bridge mode
17	○	Hi-Z	-	L	H	L	L	-	L	-		

G-S short : Gate-Emitter short

○ : OUT(H) > UVLO, X : Don't care

X : Don't care

SD : Shut down (Gate-Emitter short)

- : Specified in other items

■ Absolute Maximum Ratings

Item	Symbol	Min	Max	Unit	Conditions · Note	
Input voltage for DC/DC converter	V _{IN}	-0.3	28	Vdc	Between VIN(+) to VIN(-)	
Input voltage for Gate driver	V _{CC}	-0.3	28	Vdc	Between VCC to GND	
Input-side signal voltage	V _{SG}	-0.3	V _{CC} +0.3 or 18 *	V	INA, INB *Whichever is less	
	V _{MOD}	-0.3	28	V	MOD	
	V _{RTC}	-0.3	5	V	RTC	
Maximum gate current	I _{GP} EAK	-	43	A		
Switching frequency	F _{SW}	-	40	kHz	See the permissible frequency curve	
Short circuit detection pin voltage	V _{SD}	0	1700	V		
Alarm signal output pin maximum voltage	V _{ALM}	-0.3	V _{CC} +0.3 or 28 *	V	ALM1,2 *Whichever is less	
Input-side signal maximum current	I _{ALM}	-	5	mA	ALM1,2	
Operating temperature range	V _{IN} =13.5-18V	T _{OP}	-40	85	°C	See the permissible frequency curve
	V _{IN} =18-26.4V	T _{OP}	-40	75	°C	
Operating humidity	RH _{OP}	20	95	%RH	No condensation	
Storage temperature range	T _{STG}	-40	90	°C		
Storage humidity	RH _{STG}	5	95	%RH	No condensation	

■ Recommended Operating Conditions

Item	Symbol	Min	Max	Unit	Conditions · Note
Input voltage range for DC/DC converter	V _{IN}	13.5	26.4	Vdc	
Input voltage range for gate driver	V _{CC}	13.5	26.4	Vdc	
Driver circuit number	N	-	2	-	
Maximum gate charge	Q _G	-	5500	nC	*1
Switching frequency (Q _G =5500nC)	F _{SW}	-	16	kHz	See the permissible frequency curve
MOD pin high input voltage	V _{MODH}	3.3	26.4	V	
MOD pin low input voltage	V _{MODL}	-0.3	0.5	V	
2EGxxxCx1xN					
Logic high level input voltage	V _{SGH}	3.3	V _{CC} +0.3 or 16 *	V	INA, INB *Whichever is less
Logic low level input voltage	V _{SGL}	-0.3	0.5	V	INA, INB
Source current of control signal	I _{SG}	3.2	-	mA	INA, INB V _{SG} =15V
2EGxxxDx1xN					
Logic high level input voltage	V _{SGH}	13	V _{CC} +0.3 or 16 *	V	INA, INB *Whichever is less
Logic low level input voltage	V _{SGL}	-0.3	0.5	V	INA, INB
Source current of control signal	I _{SG}	3.3	-	mA	INA, INB V _{SG} =15V

*1 If the gate charge exceeds the allowable value, the gate voltage at turn-on and turn-off will drop, which may affect the switching performance of the SiC MOSFET.

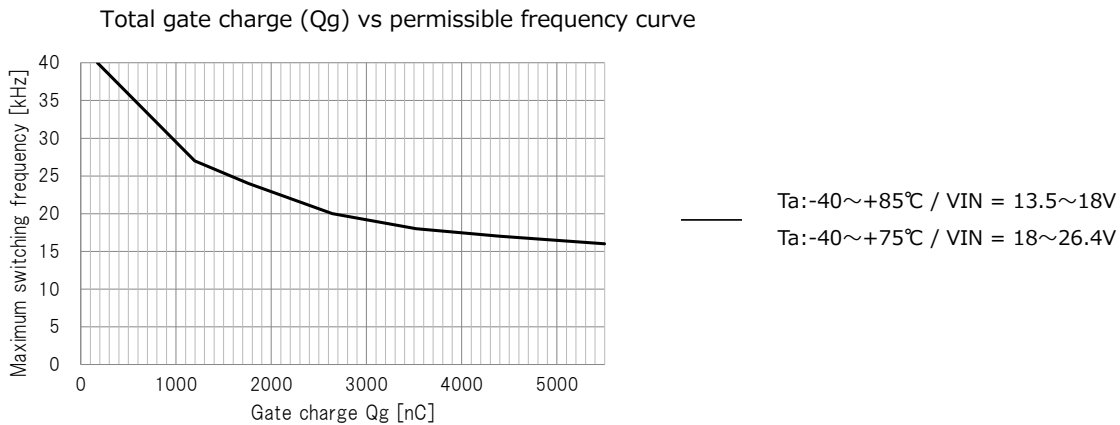
If you are considering using it under conditions other than the recommended conditions, please contact us.

■ Permissible frequency curve

Gate resistor power derating is not included.

Use the output power in a range with sufficient margin for the allowable power of the gate resistor.

Recommended resistor surface temperature : 120°C or less.



■ Electrical Specification (Vin=Vcc=15V.Ta=25°C, Unless otherwise specified)

Item	Symbol	Min	Typ	Max	Unit	Conditions · Note
DC/DC converter						
Start-up voltage	V _{START}	-	11.5	12.5	V	
Input current	I _{IN}	-	0.2	-	A	Fsw=12kHz / Test load: 106.8nF
Standby power	P _{STBY}	-	1.1	-	W	No load
Logic inputs for 2EGxxxCx1xN						
Turn-on threshold	V _{SGH}	-	2	2.3	V	INA, INB / Guaranteed by design
Turn-off threshold	V _{SGL}	0.8	1	-	V	INA, INB / Guaranteed by design
Logic pull-down resistance	R _{SGD}	-	4700	-	Ω	INA, INB
Logic inputs for 2EGxxxDx1xN						
Turn-on threshold	V _{SGH}	-	10	11.8	V	INA, INB / Guaranteed by design
Turn-off threshold	V _{SGL}	3.9	5	-	V	INA, INB / Guaranteed by design
Logic pull-down resistance	R _{SGD}	-	4500	-	Ω	INA, INB
Gate driver output						
Output pin voltage(High)	V _{OUTH}	14	15	16	V	No load
Output pin voltage(Low)	V _{OUTL}	-8	-7	-6	V	No load
Gate resistance	Rg(ON)	-	OPEN	-	Ω	No mounting / Lead resistor can be mounted.
	Rg(OFF)	-	OPEN	-		
Auxiliary gate capacitance	Cge	-	33	-	nF	
Delay time	Turn ON time	t _{PON}	-	130	-	ns
	Turn OFF time	t _{POFF}	-	130	-	ns
Dead time	t _{DEAD}	-	3	-	us	Half bridge mode

■ Protection

Item	Symbol	Min	Typ	Max	Unit	Conditions · Note
DC/DC converter						
Overload protection	-	9.2	-	-	W	Auto recovery
Overheat protection	-	120	-	150	°C	Auto recovery, Internal temperature
Gate driver						
Output voltage(H) UVLO OFF voltage	V_{UVLOOH}	13.2	13.5	13.8	V	Guaranteed by design
Output voltage(H) UVLO ON voltage	V_{UVLOOH}	12.2	12.5	12.8	V	Guaranteed by design
Short circuit detection voltage	V_{SD}	-	9.5	-	V	
Short circuit detection filter time	$t_{SHORTFIL}$	-	1.5	-	us	Collector open
Alarm signal output L voltage	V_{ALML}	-	-	0.5	V	$I_{ALM}=5mA$
Alarm signal response time	t_{ALM}	-	0.2	-	us	
Restart time	$t_{RESTART}$	-	110	-	ms	
Soft turn-off resistance	R_{STO}	-	2.2	-	Ω	
Soft turn-off duration	t_{STO}	-	4	-	us	
Miller clamp voltage	V_{CLAMP}	-	1.2	-	V	$I_{CLAMP}=500mA$, Guaranteed by design
Miller clamp ON threshold voltage	V_{CLPON}	-	$V_{GL}+2$	-	V	

■ Insulation

Item	Specification	Conditions · Note
Between Input-Output		
Dielectric withstand voltage	AC5000V	1min, Cutoff 2mA
Insulation resistance	100M Ω or more	DC500V
Partial discharge extinction voltage	1768Vpeak or more	According to EN50178/IEC 60270
Common-mode transient immunity (CMTI)	70kV/us	
Minimum clearance distances	12mm	As for Gate driver PCB
Minimum creepage distances	16mm	
Between Input-Output / SiC MOSFET device terminal - Gate driver PCB Input side		
Minimum clearance distances	11mm	MITSUBISHI / NX package
Minimum creepage distances	12mm	
Between CH1-CH2		
Minimum clearance distances	7mm	Excluding electrical connections point
Minimum creepage distances	12mm	

■ Storage Conditions

Item	Min	Max	Unit	Conditions · Note
Storage temperature	-25	60	°C	A packing state

※If you want to use past the long period there is a concern that the solder non-wetting by terminal oxidation to occur.
Therefore, please use from taking enough tests.

■ Recommended Soldering Condition

- Soldering condition of hand work : 360°C(MAX) Less than 5sec

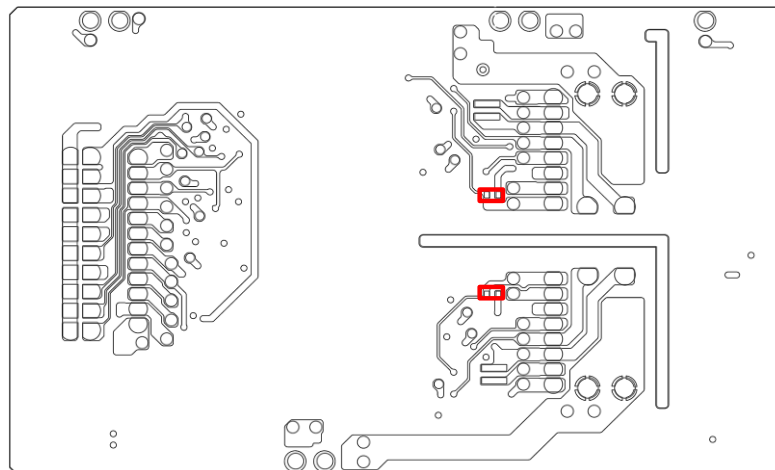
■ Recommended gate resistance value

Item	Symbol	Min	Max	Unit	Conditions · Note
Recommended gate resistance value	Rg(ON)	1.6	8	Ω	FMF600DXE-24BN (Mitsubishi)
	Rg(OFF)	1.2	8		
	Rg(ON)	1.2	6	Ω	FMF600DXE-34BN (Mitsubishi)
	Rg(OFF)	4.7	6		

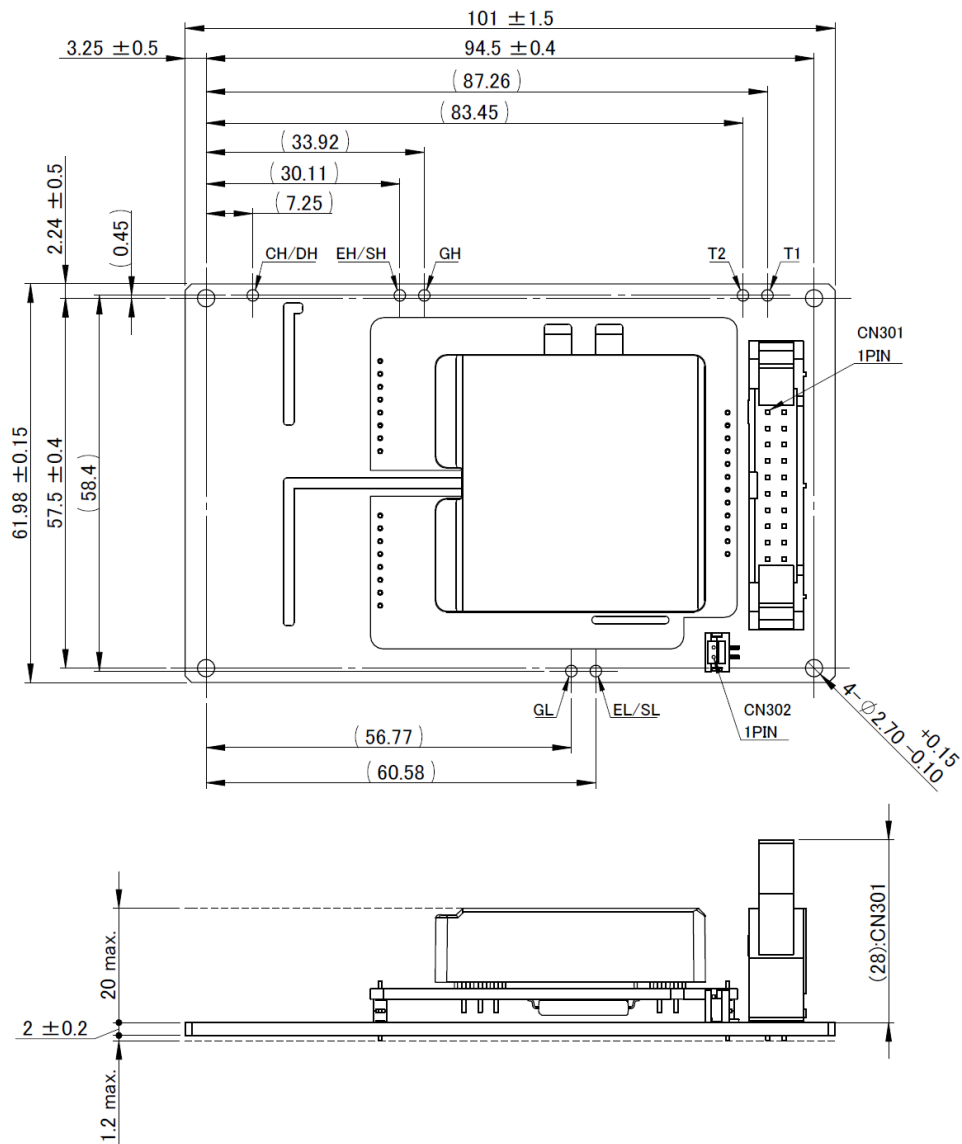
■ Usage Cautions

- Always mount fuse on the plus side of input for ensuring safety because the fuse is not built-in the product.
Please select the fuse considering conditions such as steady current, inrush current, and ambient temperature.
When using a fuse having large rated current or high capacity input electrolytic condenser, by combining another converter and input line and input electrolytic condenser, fuse may not blow off in the case of abnormality.
Do not combine high voltage line and fuse.
- Make sure the rise/fall time of the input signal is 500ns or less.
Also, keep input wiring as far as possible from noise sources.
To prevent malfunction due to noise, a high signal voltage within the recommended range is recommended.
- Please do not apply excessive stress to this product when attaching to SiC MOSFET power module.
- This product has DESAT protection for arm short circuit and load short circuit protection.
However, even if this protection works, the SiC MOSFET may be damaged if abnormally high current occurs due to SiC MOSFET's characteristics variations or the load short-circuit mode during parallel operation.
To ensure safety, be sure to check the short-circuit current at the unit in which this product is integrated, and evaluate whether it can protect under the condition that there is no damage to the SiC MOSFET.
- When ALM outputs Low, it may cause abnormality to the system, so confirm the abnormality immediately.
- When using with FMF600DXE-34BN (Mitsubishi), do not use the desaturation protection function.
The DESAT function can be disabled by mounting a 0Ω (1608 size) in the area enclosed in the red frame in the figure below.
Since the protection function will not be activated when an overcurrent occurs due to an arm short circuit or load short circuit in the power semiconductor, please implement safety measures on the device side.

[2EG01XBxN18N bottom view]



■ Outline Dimensional Drawing



Unit: mm

Note: 1. The dimensional tolerance without directions is ± 0.5 mm.

■ Product Weight

72.0g(typ)

■ Important Notice

- This information and product are subject to change without prior notice for the purpose of improvements, etc. Ensure that you are in possession of the most up-to-date information when using this product.
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When applying this product to your devices or systems, please ensure that you conduct evaluations of their state when integrated with this product. You are responsible for judging its applicability.
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 - Use in liquids such as water, oil, chemical solutions, or organic solvents, and use in locations where the product will be exposed to such liquids.
 - Use that involves exposure to direct sunlight, outdoor exposure, or dusty conditions.
 - Use in locations where corrosive gases such as salt air, C12, H2S, NH3, SO2, or NO2, are present.
 - Use in environments with strong static electricity or electromagnetic radiation.
 - Use that involves placing inflammable material next to the product.
 - Use of this product either sealed with a resin filling or coated with resin.
 - Use of water or a water soluble detergent for flux cleaning.
 - Use in locations where condensation is liable to occur.
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